

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application.

LISTING OF CLAIMS:

1. - 6. (Canceled)

7. (Currently Amended) A method of manufacturing electronic parts, comprising the steps of:

providing a holding jig made of an elastic material, wherein at least one surface of said elastic material is adhesive and the hardness of the elastic material is a rubber hardness degree of at least A30;

mounting a substrate on the holding jig by an adhesive strength of said surface of the elastic material;

mounting an element onto said substrate and electrically connecting the element to said substrate while the substrate is held on the surface of the elastic material; and

applying ultrasonic waves to a bonding portion at which the electric connection is performed while the substrate is held on the surface of the elastic material.

8. - 9. (Canceled).

10. (Currently Amended) The method of manufacturing electronic parts according to claim ~~[[9]]~~ 7, wherein the step of holding said substrate includes using the holding jig which comprises heat-resistant material having a heat-resistance temperature of about 250°C.

11. (Currently Amended) The method of manufacturing electronic parts according to claim ~~[[9]]~~ 7, wherein the step of holding said substrate includes using the holding jig which includes a laminate structure of a hard plate and the elastic material.

12. (Currently Amended) The method of manufacturing electronic parts according to claim ~~[[9]]~~ 7, wherein the elastic material comprises silicone resin.

13. (Currently Amended) The method of manufacturing electronic parts according to claim ~~[[9]]~~ 7, wherein the mounting process includes a wire bonding process.

14. (Currently Amended) The method of manufacturing electronic parts according to claim ~~[[9]]~~ 7, wherein the mounting process includes a bump bonding process.

15. - 18. (Canceled)

19. (Previously Presented) The method of manufacturing electronic parts according to claim 7 wherein the adhesive strength of the surface of the elastic material is 1 to 10 g/mm².